

HIGH RELIABILITY THERMAL CURING SYSTEM 200MM SMIF ULTRA-CLEAN VACUUM CURING OVENS

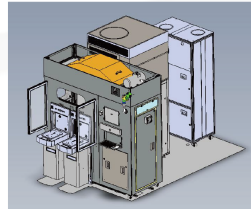
FVO-450 Series Superior Performance

- Class 10 Ultra Clean Curing Chamber
- Full Automation
- Up To 450 °C Curing Temperature At ± 3 °C
- Maximum Heating Ramp 6 °C/Minute and Cooling Ramp 4 °C/minute
- Process under vacuum (10 torr) with 1~3 gases
- Field Qualified Install bases worldwide

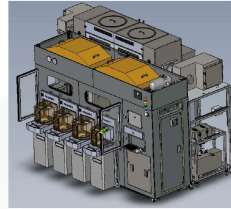


Energy Saving and Low Operation Cost

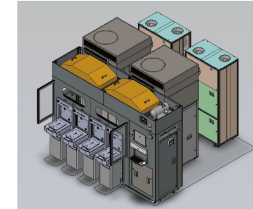
- Air cooling → Low energy
- 80% nitrogen savings



FVO-450-1
Single-Chamber (50 wafers)



FVO-450-G2
High Precision Dual-Chamber



FVO-450-2
Dual-Chamber (100 wafers)

Qualified Process

- | | | |
|----------------------------|-----------------------|------------------------|
| ■ 2.5D / 3DIC profile cure | ■ Thermal Cure | ■ Photoresist Cure |
| ■ Anneal | ■ Moisture Removed | ■ Copper Anneal |
| ■ PI Cure | ■ Photoresist Removed | ■ Copper Oxide Removed |
| ■ BCB Cure | ■ Re-flow | |



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